



Material Content Data Sheet



Sales Product Name				BSZ050N03LS G		Issued		20. July 2018	
MA#				MA001684532					
Package				PG-TSDSON-8-2		Weight*		39.77 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.213	3.05	3.05	30491	30491	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53		
	non noble metal	zinc	7440-66-6	0.008	0.02		211		
	non noble metal	iron	7439-89-6	0.168	0.42		4216		
wire	non noble metal	copper	7440-50-8	6.808	17.12	17.57	171190	175670	
	non noble metal	copper	7440-50-8	0.037	0.09	0.09	930	930	
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.10		950	
	plastics	epoxy resin	-	1.946	4.89		48935		
	inorganic material	silicondioxide	60676-86-0	16.909	42.53	47.52	425206	475091	
leadfinish	non noble metal	tin	7440-31-5	0.387	0.97	0.97	9735	9735	
plating	noble metal	silver	7440-22-4	0.963	2.42	2.42	24206	24206	
solder	non noble metal	tin	7440-31-5	0.028	0.07		708		
	noble metal	silver	7440-22-4	0.035	0.09		886		
	non noble metal	lead	7439-92-1	1.345	3.38	3.54	33828	35422	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.086	0.22		2168		
	non noble metal	copper	7440-50-8	3.501	8.80	9.03	88042	90345	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		190		
	non noble metal	iron	7439-89-6	0.151	0.38		3795		
	non noble metal	copper	7440-50-8	6.127	15.41	15.81	154078	158110	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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